

# Octal D Flip-Flop MC74AC273, MC74ACT273

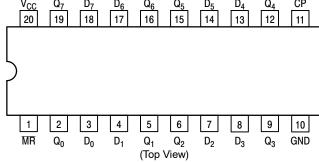
The MC74AC273/74ACT273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset  $(\overline{MR})$  inputs load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the  $\overline{MR}$  input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

#### **Features**

- Ideal Buffer for MOS Microprocessor or Memory
- Eight Edge-Triggered D Flip-Flops
- Buffered Common Clock
- Buffered, Asynchronous Master Reset
- See MC74AC377 for Clock Enable Version
- See MC74AC373 for Transparent Latch Version
- See MC74AC374 for 3-State Version
- Outputs Source/Sink 24 mA
- 'ACT273 Has TTL Compatible Inputs
- These are Pb-Free Devices



Pinout: 20-Lead Packages Conductors

### MODE SELECT-FUNCTION TABLE

Operating Mode		Inputs	Outputs	
Operating Mode	MR	CP	D <sub>n</sub>	Qn
Reset (Clear)	L	Х	Х	L
Load '1'	Н	۲	Н	Н
Load '0'	Н	7	L	L

H = HIGH Voltage Level

L = LOW Voltage Level

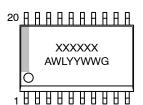
X = Immaterial

\_ = LOW-to-HIGH Clock Transition

### MARKING DIAGRAMS

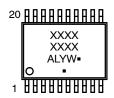


SOIC-20W DW SUFFIX CASE 751D





TSSOP-20 DT SUFFIX CASE 948E



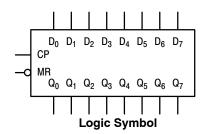
XXXXXX = Specific Device Code A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

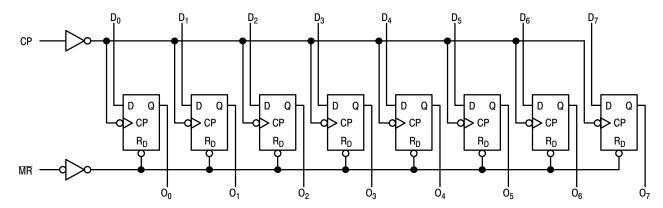
### **PIN ASSIGNMENT**

PIN	FUNCTION
D <sub>0</sub> -D <sub>7</sub>	Data Inputs
MR	Master Reset
СР	Clock Pulse Input
Q <sub>0</sub> -Q <sub>7</sub>	Data Outputs



#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.



NOTE: That this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Figure 1. Logic Diagram

#### **MAXIMUM RATINGS**

Symbol	Paramet	er	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)		-0.5 to +6.5	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)		-0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND) (No	ote 1)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	DC Input Diode Current		±20	mA
I <sub>OK</sub>	DC Output Diode Current		±50	mA
I <sub>OUT</sub>	DC Output Sink/Source Current		±50	mA
I <sub>CC</sub>	DC Supply Current, per Output Pin		±50	mA
I <sub>GND</sub>	DC Ground Current, per Output Pin		±100	mA
T <sub>STG</sub>	Storage Temperature Range		-65 to +150	°C
$T_L$	Lead temperature, 1 mm from Case for 10 Se	econds	260	°C
TJ	Junction Temperature Under Bias		140	°C
θЈА	Thermal Resistance (Note 2)	SOIC TSSOP	96 150	°C/W
MSL	Moisture Sensitivity	SOIC TSSOP	Level 3 Level 1	
F <sub>R</sub>	Flammability Rating	Oxygen Index: 30% - 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage	Human Body Model (Note 3) Charged Device Model (Note 4)	> 2000 > 1000	V
I <sub>Latchup</sub>	Latchup Performance Above	V <sub>CC</sub> and Below GND at 85°C (Note 5)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I<sub>OUT</sub> absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD 51-7.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
.,,	/cc Supply Voltage		2.0	5.0	6.0	V
V <sub>CC</sub>	Supply Voltage	'ACT	4.5	5.0	5.5	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V <sub>CC</sub>	V
		V <sub>CC</sub> @ 3.0 V	-	150	-	
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 6)  'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	-	40	-	ns/V
	The Bevious except commit impute	V <sub>CC</sub> @ 5.5 V	-	25	-	
	Input Rise and Fall Time (Note 7)	V <sub>CC</sub> @ 4.5 V	-	10	-	0 /
t <sub>r</sub> , t <sub>f</sub>	'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 5.5 V	-	8.0	-	ns/V
T <sub>A</sub>	Operating Ambient Temperature Range		-40	25	85	°C
I <sub>OH</sub>	Output Current – High		-	-	-24	mA
I <sub>OL</sub>	Output Current – Low		-	-	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

- 6. V<sub>IN</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.
   7. V<sub>IN</sub> from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

### **DC CHARACTERISTICS**

		74AC		74AC			
Symbol	Parameter	V <sub>CC</sub>	T <sub>A</sub> = -	+25°C	T <sub>A</sub> = -40°C to +85°C	Unit	Conditions
		(V)	Тур	Gu	aranteed Limits		
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	>	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	>	I <sub>OUT</sub> = -50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	٧	$\begin{tabular}{lllllllllllllllllllllllllllllllllll$
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$^{*}V_{IN} = V_{IL} \text{ or } V_{IH}$ $^{12} \text{ mA}$ $^{1}OL$ $^{24} \text{ mA}$ $^{24} \text{ mA}$
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND
I <sub>OLD</sub> I <sub>OHD</sub>	†Minimum Dynamic Output Current	5.5 5.5	-	_ _	75 –75	mA	V <sub>OLD</sub> = 1.65 V Max V <sub>OHD</sub> = 3.85 V Min
Icc	Maximum Quiescent Supply Current	5.5	-	8.0	80	μΑ	V <sub>IN</sub> = V <sub>CC</sub> or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

### **AC CHARACTERISTICS**

				74AC		74	AC	
Symbol	Parameter	V <sub>CC</sub> * (V)				35°C C <sub>L</sub> = 50 pF	Unit	
		(•)	Min	Тур	Max	Min	Max	
f <sub>max</sub>	Maximum Clock Frequency	3.3 5.0	90 140	125 175	-	75 125	-	Mhz
t <sub>PLH</sub>	Propagation Delay Clock to Output	3.3 5.0	4.0 3.0	7.0 5.5	12.5 9.0	3.0 2.5	14.0 10.0	ns
t <sub>PHL</sub>	Propagation Delay Clock to Output	3.3 5.0	4.0 3.0	7.0 5.0	13.0 10.0	3.5 2.5	14.5 11.0	ns
t <sub>PHL</sub>	Propagation Delay MR to Output	3.3 5.0	4.0 3.0	7.0 5.0	13.0 10.0	3.5 2.5	14.0 10.5	ns

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

### **AC OPERATING REQUIREMENTS**

			74	AC	74AC	
Symbol	Parameter	V <sub>CC</sub> * (V)	T <sub>A</sub> = +25°C	$T_A = +25^{\circ}C C_L = 50 \text{ pF}$ $T_A = -40^{\circ}C \text{ to } +85^{\circ}C C_L = 50$		Unit
		(•)	Тур		Guaranteed Minimum	
t <sub>s</sub>	Setup Time, HIGH or LOW Data to CP	3.3 5.0	3.5 2.5	5.5 4.0	6.0 4.5	ns
t <sub>h</sub>	Hold Time, HIGH or LOW Data to CP	3.3 5.0	-2.0 -1.0	0 1.0	0 1.0	ns
t <sub>w</sub>	Clock Pulse Width HIGH or LOW	3.3 5.0	3.5 2.5	5.5 4.0	6.0 4.5	ns
t <sub>w</sub>	MR Pulse Width HIGH or LOW	3.3 5.0	2.0 1.5	5.5 4.0	6.0 4.5	ns
t <sub>rec</sub>	Recovery Time MR to CP	3.3 5.0	1.5 1.0	3.5 2.0	4.5 3.0	ns

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

NOTE: Note:  $I_{IN}$  and  $I_{CC}$  @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V  $V_{CC}$ .

### **DC CHARACTERISTICS**

			74	CT	74ACT		
Symbol	Parameter $V_{CC}$ $T_A = +25^{\circ}C$		T <sub>A</sub> = -40°C to +85°C	Unit	Conditions		
			Тур	Gua	ranteed Limits		
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
$V_{IL}$	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	٧	I <sub>OUT</sub> = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	٧	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $I_{OH} = -24 \text{ mA}$ $= -24 \text{ mA}$
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		4.5 5.5	- -	0.36 0.36	0.44 0.44	٧	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ 24 mA $I_{OL}$ 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	5.5	0.6	-	1.5	mA	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V
I <sub>OLD</sub> I <sub>OHD</sub>	†Minimum Dynamic Output Current	5.5 5.5	- -	- -	75 -75	mA	V <sub>OLD</sub> = 1.65 V Max V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	_	8.0	80	μΑ	V <sub>IN</sub> = V <sub>CC</sub> or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

### **AC CHARACTERISTICS**

		74ACT			74.6			
Symbol	Parameter	V <sub>CC</sub> * (V)	T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF			T <sub>A</sub> = -40°C to +85°C C <sub>L</sub> = 50 pF		Unit
			Min	Тур	Max	Min	Max	
f <sub>max</sub>	Maximum Clock Frequency	5.0	125	200	-	125	-	MHz
t <sub>PHL</sub>	Propagation Delay Clock to Output	5.0	3.0	6.0	10	2.5	11.0	ns
t <sub>PLH</sub>	Propagation Delay Clock to Output	5.0	3.0	6.5	11	2.5	12.0	ns
t <sub>PHL</sub>	Propagation Delay MR to Output	5.0	3.0	7.0	11	2.5	11.5	ns

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V ±0.5 V.

### **AC OPERATING REQUIREMENTS**

			744	CT	74ACT	
Symbol	Parameter		T <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF		T <sub>A</sub> = -40°C to +85°C C <sub>L</sub> = 50 pF	Unit
			Тур	Guara	inteed Minimum	
t <sub>s</sub>	Setup Time, HIGH or LOW – Data to CP	5.0	3.0	4.5	5.0	ns
t <sub>h</sub>	Hold Time, HIGH or LOW - Data to CP	5.0	-2.5	2.0	2.0	ns
t <sub>w</sub>	Clock Pulse Width - HIGH or LOW	5.0	2.5	4.0	4.5	ns
t <sub>w</sub>	MR Pulse Width – HIGH or LOW	5.0	2.5	4.0	4.5	ns
t <sub>rec</sub>	Recovery Time – MR to CP	5.0	-1.0	2.0	3.0	ns

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V ±0.5 V.

### **CAPACITANCE**

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	50	pF	V <sub>CC</sub> = 5.0 V

### **ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
MC74AC273DWG	AC273	SOIC-20WB	38 Units / Rail
MC74AC273DWR2G	AC273	SOIC-20WB	1000 / Tape & Reel
MC74AC273DTR2G	AC 273	TSSOP-20	2500 / Tape & Reel
MC74ACT273DWG	ACT273	SOIC-20WB	38 Units / Rail
MC74ACT273DWR2G	ACT273	SOIC-20WB	1000 / Tape & Reel
MC74ACT273DTR2G	ACT 273	TSSOP-20	2500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

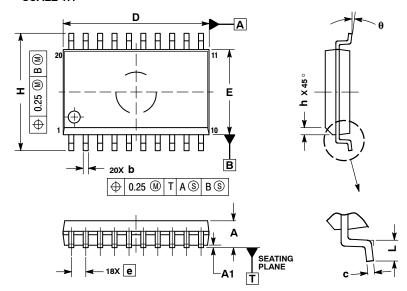




SOIC-20 WB CASE 751D-05 **ISSUE H** 

**DATE 22 APR 2015** 

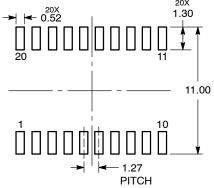
### SCALE 1:1



- DIMENSIONS ARE IN MILLIMETERS.
   INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

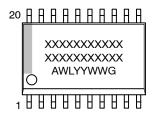
	MILLIMETERS		
DIM	MIN	MAX	
Α	2.35	2.65	
A1	0.10	0.25	
b	0.35	0.49	
С	0.23	0.32	
D	12.65	12.95	
E	7.40	7.60	
е	1.27 BSC		
Н	10.05	10.55	
h	0.25	0.75	
L	0.50	0.90	
A	0 °	7 °	

### **RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SOIC-20 WB		PAGE 1 OF 1

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